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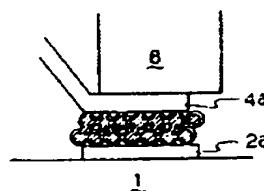
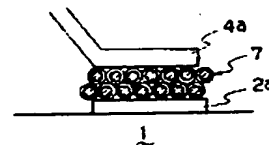
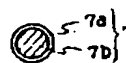
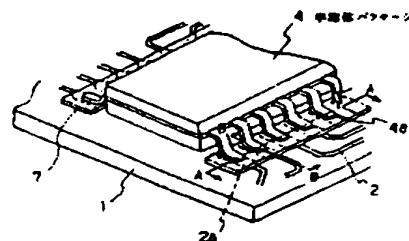
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H05K 3/32

TITLE : TERMINAL CONNECTING
MICROCAPSULE FOR
SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To electrically and mechanically connect a semiconductor package to a printed board even if a mounting density is improved by composing of an outer shell made of a film to be cracked by a predetermined temperature and/or predetermined pressure and an interior made of heat fusible conductive substance.

CONSTITUTION: An outer shell 7a made of a film to be cracked by a predetermined temperature and/or predetermined pressure is provided, an interior 7b made of heat fusible conductive substance is melted and discharged from a microcapsule 7 to be cracked due to heating, etc., and a junction 2a is bonded to outer leads 4a. That is, a semiconductor package 4 is placed on a board 1 coated in a stripe state with the microcapsules 7, the shell 7a of the microcapsule 7 is cracked due to heating by a bonding tool 8 to melt and discharge the interior 7b, which is dissolved with the interior 7b melted and discharged similarly from other microcapsule 7. Thus, even if its pitch is reduced, a bonding material in which the junction 7a can be bonded to the leads 4a can be obtained.

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